

ABSTRACT

There is provided a process for producing a multilayer for a multilayer electronic device, including a dielectric layer and an electrode layer, which process is improved so as to prevent penetration of an electrode paste into the dielectric layer as well as deformation of the dielectric layer and electrode layer, allow raw material sheets required for producing the respective layers such as an adhesive layer-forming sheet to be used in the form of a roll without problems such as back transfer (offset), and allow a multilayer sheet having an adhesive layer to be produced in the form of a roll without problems such as back transfer (offset). In the process of the present invention, transfer steps (first to third steps) and an adhesion step (fourth step) are successively conducted using a green sheet roll (1), an adhesive layer-forming roll (2) and an electrode layer-forming roll (3) which have respective specific layer structures, to produce a roll (4) of a multilayer sheet (40) having a layer structure composed of a first substrate sheet/a release layer/a print-assisting layer/an electrode-spacer layer/an adhesive layer/a dielectric layer/[an adhesive layer/a release layer/a second substrate layer/a back transfer (offset)-preventing layer].